



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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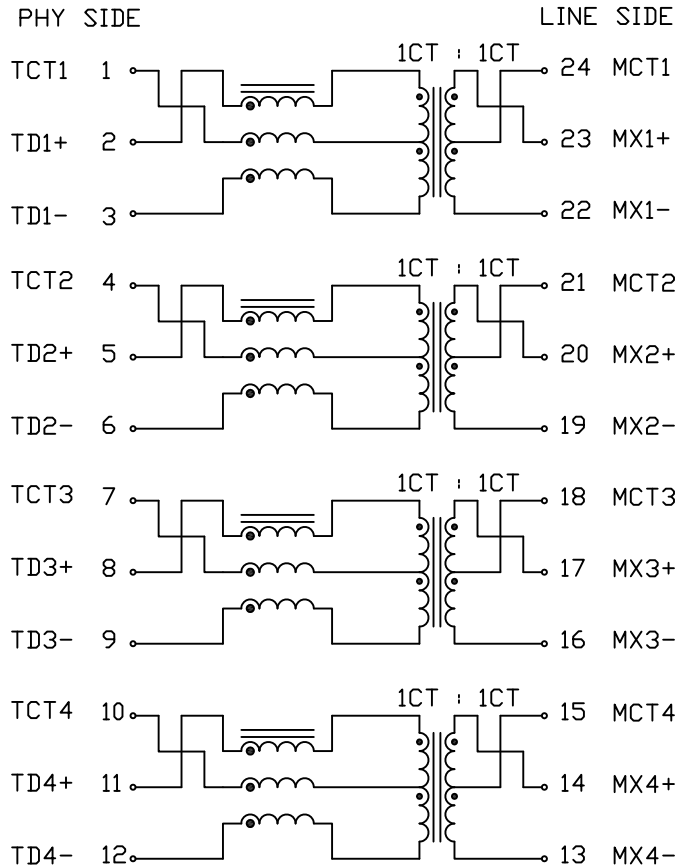
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PRELIMINARY

ELECTRICAL CHARACTERISTICS @25°C



SCHEMATIC



URNS RATIO
 (2-1-3) : (23-24-22)
 (5-4-6) : (20-21-19)
 (8-7-9) : (17-18-16)
 (11-10-12) : (14-15-13)

1CT : 1CT ±2%
 1CT : 1CT ±2%
 1CT : 1CT ±2%
 1CT : 1CT ±2%

POLARITY
 DCL

PER DOT CONVENTION

100kHz, 100mV
 180µH MIN WITH 8mA DC BIAS
 120µH MIN WITH 19mA DC BIAS

RETURN LOSS
 1MHz-100MHz
 100MHz-300MHz

-20 dB Min
 -20+16LOG(f/100MHz) dB MIN

HIPOT (Isolation Voltage):
 100% OF PRODUCTION TESTED TO COMPLY WITH
 IEEE 802.3 ISOLATION REQUIREMENTS.
 NOTE: PORT-TO PORT ISOLATION NOT INCLUDED.
 BALANCED DC LINE CURRENT

2250 VDC

720 mA MAX. @ 57 VDC CONTINUOUS
 1.2mA MAX. @ 57 VDC FOR 200 MILLISECONDS

OPERATING TEMPERATURE: -40 TO 85°C

MEETS 5G PERFORMANCE REQUIREMENTS AS PER IEEE 802.3bz

REV. : X PAGE : 2

ORIGINATED BY	DATE
Alice Pang	2016-10-28
DRAWN BY	DATE
JB	2017-08-10

TITLE
ELECTRICAL SPECIFICATION

PART NO. / DRAWING NO.
S558-5500-JV
FILE NAME
S5585500JVPA.DWG

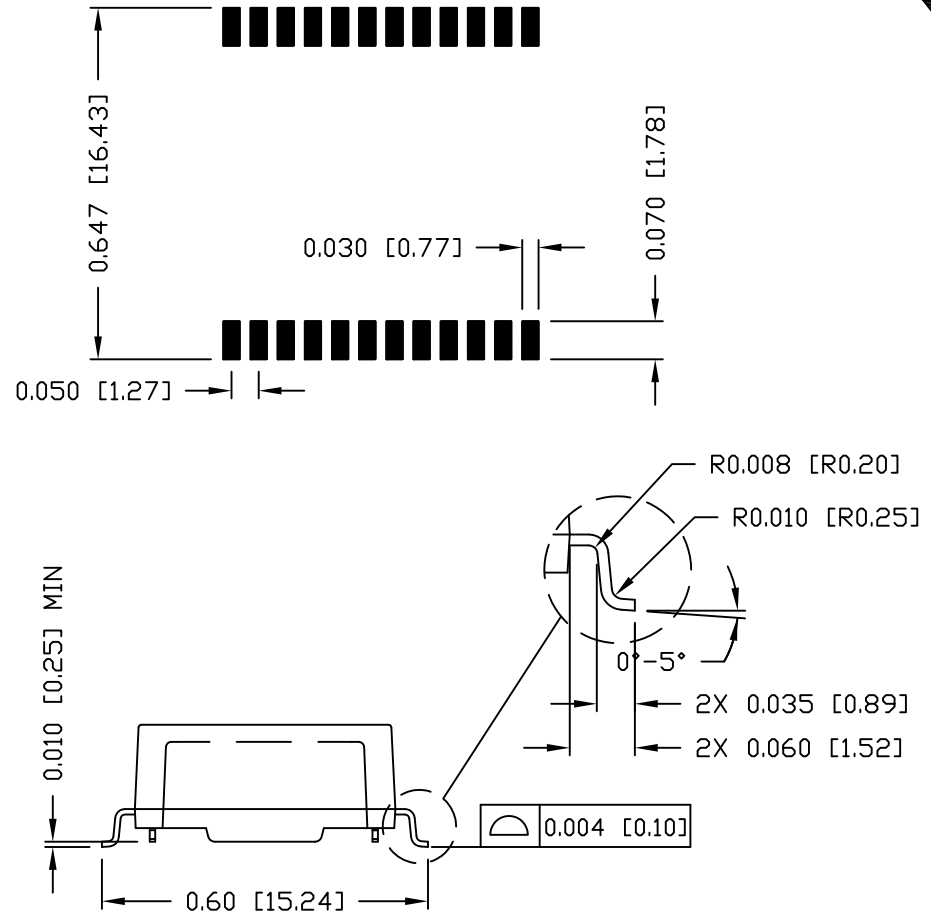
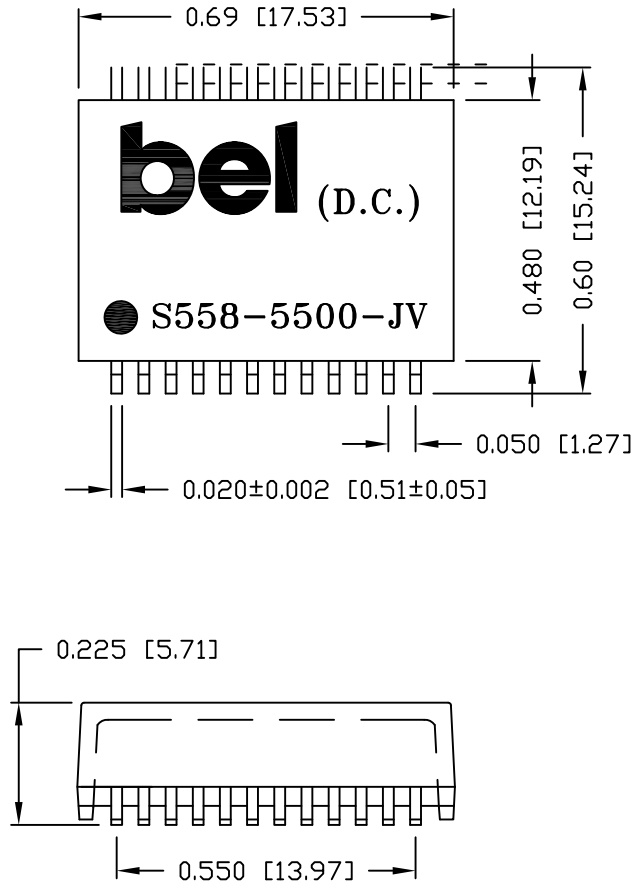
STANDARD DIM.	[] METRIC DIM. AS REF.
TOL. IN INCH	UNIT : INCH [mm]
.X	SCALE : N/A
.XX	SIZE : A4
.XXX	



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PRELIMINARY

SUGGESTED PCB PAD LAYOUT



NOTES:

- STANDARD MARKING REFER TO DOC. HAND-WORK-04.
- PACKAGE CODE: "RQS001".

REV. : PA	PAGE : 3

ORIGINATED BY	DATE	TITLE	PART NO. / DRAWING NO.	STANDARD DIM.		[] METRIC DIM. AS REF.	
Lawrence Tsang	2016-10-28			MECHANICAL OUTLINE	S558-5500-JV	TOL. IN INCH	UNIT : INCH [mm]
DRAWN BY	DATE					FILE NAME	.X
ZC Guo	2016-10-28	S5585500JVPA.DWG	.XX ±0.01			SIZE : A4	
				.XXX ±0.005			

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